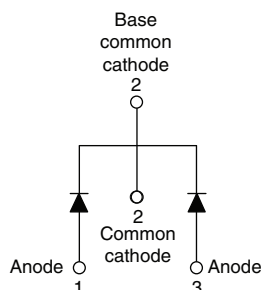


# **HEXFRED®** **Ultrafast Soft Recovery Diode, 2 x 15 A**


**TO-220AB**


## **FEATURES**

- Ultrafast and ultrasoft recovery
- Very low  $I_{RRM}$  and  $Q_{rr}$
- Designed and qualified according to JEDEC®-JESD47
- Material categorization:  
for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**  
Available

## **BENEFITS**

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

## **DESCRIPTION**

VS-HFA30TA60C... is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 15 A per leg continuous current, the VS-HFA30TA60C... is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current ( $I_{RRM}$ ) and does not exhibit any tendency to “snap-off” during the  $t_b$  portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA30TA60C... is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

## **PRODUCT SUMMARY**

|                 |                |
|-----------------|----------------|
| Package         | TO-220AB       |
| $I_{F(AV)}$     | 2 x 15 A       |
| $V_R$           | 600 V          |
| $V_F$ at $I_F$  | 1.2 V          |
| $t_{rr}$ typ.   | 19 ns          |
| $T_J$ max.      | 150 °C         |
| Diode variation | Common cathode |

## **ABSOLUTE MAXIMUM RATINGS**

| PARAMETER                                        | SYMBOL         | TEST CONDITIONS       | VALUES      | UNITS |
|--------------------------------------------------|----------------|-----------------------|-------------|-------|
| Cathode to anode voltage                         | $V_R$          |                       | 600         | V     |
| Maximum continuous forward current               | $I_F$          | $T_C = 100\text{ °C}$ | 15          | A     |
|                                                  |                |                       | 30          |       |
| Single pulse forward current                     | $I_{FSM}$      |                       | 150         |       |
| Maximum repetitive forward current               | $I_{FRM}$      |                       | 60          |       |
| Maximum power dissipation                        | $P_D$          | $T_C = 25\text{ °C}$  | 74          | W     |
|                                                  |                | $T_C = 100\text{ °C}$ | 29          |       |
| Operating junction and storage temperature range | $T_J, T_{Stg}$ |                       | -55 to +150 | °C    |

**ELECTRICAL SPECIFICATIONS PER LEG** ( $T_J = 25\text{ }^{\circ}\text{C}$  unless otherwise specified)

| PARAMETER                          | SYMBOL   | TEST CONDITIONS                                                        | MIN. | TYP. | MAX. | UNITS         |
|------------------------------------|----------|------------------------------------------------------------------------|------|------|------|---------------|
| Cathode to anode breakdown voltage | $V_{BR}$ | $I_R = 100\text{ }\mu\text{A}$                                         | 600  | -    | -    | V             |
| Maximum forward voltage            | $V_{FM}$ | $I_F = 15\text{ A}$                                                    | -    | 1.3  | 1.7  |               |
|                                    |          | $I_F = 30\text{ A}$                                                    | -    | 1.5  | 2.0  |               |
|                                    |          | $I_F = 15\text{ A}, T_J = 125\text{ }^{\circ}\text{C}$                 | -    | 1.2  | 1.6  |               |
| Maximum reverse leakage current    | $I_{RM}$ | $V_R = V_R\text{ rated}$                                               | -    | 1.0  | 10   | $\mu\text{A}$ |
|                                    |          | $T_J = 125\text{ }^{\circ}\text{C}, V_R = 0.8 \times V_R\text{ rated}$ | -    | 400  | 1000 |               |
| Junction capacitance               | $C_T$    | $V_R = 200\text{ V}$                                                   | -    | 25   | 50   | pF            |
| Series inductance                  | $L_S$    | Measured lead to lead 5 mm from package body                           | -    | 8    | -    | nH            |

**DYNAMIC RECOVERY CHARACTERISTICS PER LEG** ( $T_J = 25\text{ }^{\circ}\text{C}$  unless otherwise specified)

| PARAMETER                                                           | SYMBOL            | TEST CONDITIONS                                                             | MIN. | TYP. | MAX. | UNITS                  |
|---------------------------------------------------------------------|-------------------|-----------------------------------------------------------------------------|------|------|------|------------------------|
| Reverse recovery time<br>See fig. 5 and 10                          | $t_{rr}$          | $I_F = 1.0\text{ A}, di_F/dt = 200\text{ A}/\mu\text{s}, V_R = 30\text{ V}$ | -    | 19   | -    | ns                     |
|                                                                     | $t_{rr1}$         | $T_J = 25\text{ }^{\circ}\text{C}$                                          | -    | 42   | 60   |                        |
|                                                                     | $t_{rr2}$         | $T_J = 125\text{ }^{\circ}\text{C}$                                         | -    | 70   | 120  |                        |
| Peak recovery current<br>See fig. 6                                 | $I_{RRM1}$        | $T_J = 25\text{ }^{\circ}\text{C}$                                          | -    | 4.0  | 6.0  | A                      |
|                                                                     | $I_{RRM2}$        | $T_J = 125\text{ }^{\circ}\text{C}$                                         | -    | 6.5  | 10   |                        |
| Reverse recovery charge<br>See fig. 7                               | $Q_{rr1}$         | $T_J = 25\text{ }^{\circ}\text{C}$                                          | -    | 80   | 180  | nC                     |
|                                                                     | $Q_{rr2}$         | $T_J = 125\text{ }^{\circ}\text{C}$                                         | -    | 220  | 600  |                        |
| Peak rate of fall of<br>recovery current during $t_b$<br>See fig. 8 | $di_{(rec)M}/dt1$ | $T_J = 25\text{ }^{\circ}\text{C}$                                          | -    | 250  | -    | $\text{A}/\mu\text{s}$ |
|                                                                     | $di_{(rec)M}/dt2$ | $T_J = 125\text{ }^{\circ}\text{C}$                                         | -    | 160  | -    |                        |

**THERMAL - MECHANICAL SPECIFICATIONS PER LEG**

| PARAMETER                                  | SYMBOL     | TEST CONDITIONS                            | MIN.         | TYP. | MAX.       | UNITS                  |
|--------------------------------------------|------------|--------------------------------------------|--------------|------|------------|------------------------|
| Lead temperature                           | $T_{lead}$ | 0.063" from case (1.6 mm) for 10 s         | -            | -    | 300        | $^{\circ}\text{C}$     |
| Junction to case,<br>single leg conducting | $R_{thJC}$ |                                            |              |      | 1.7        | K/W                    |
| Junction to case,<br>both legs conducting  |            |                                            | -            | -    | 0.85       |                        |
| Thermal resistance,<br>junction to ambient | $R_{thJA}$ | Typical socket mount                       | -            | -    | 40         |                        |
| Thermal resistance,<br>case to heatsink    | $R_{thCS}$ | Mounting surface, flat, smooth and greased | -            | 0.25 | -          |                        |
| Weight                                     |            |                                            | -            | 6.0  | -          | g                      |
|                                            |            |                                            | -            | 0.21 | -          | oz.                    |
| Mounting torque                            |            |                                            | 6.0<br>(5.0) | -    | 12<br>(10) | kgf · cm<br>(lbf · in) |
| Marking device                             |            | Case style TO-220AB                        | HFA30TA60C   |      |            |                        |

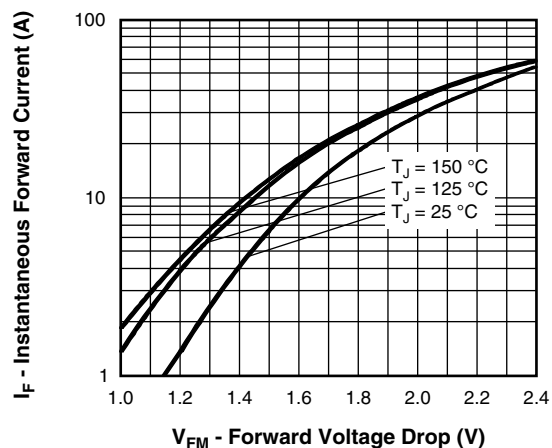


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

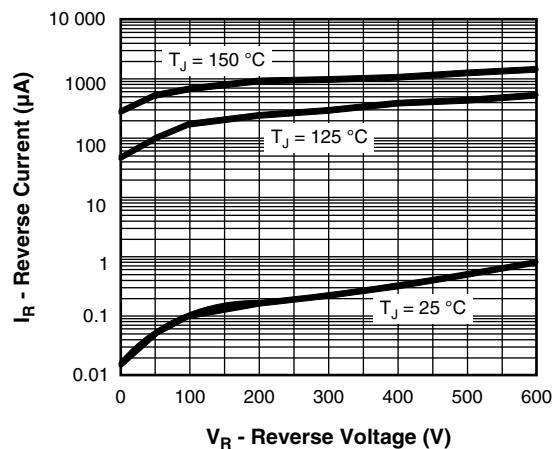


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

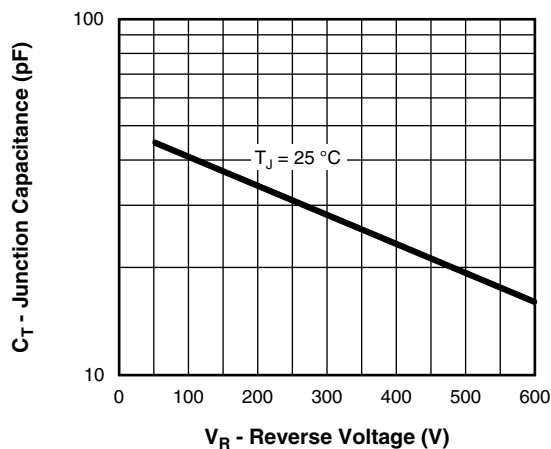


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

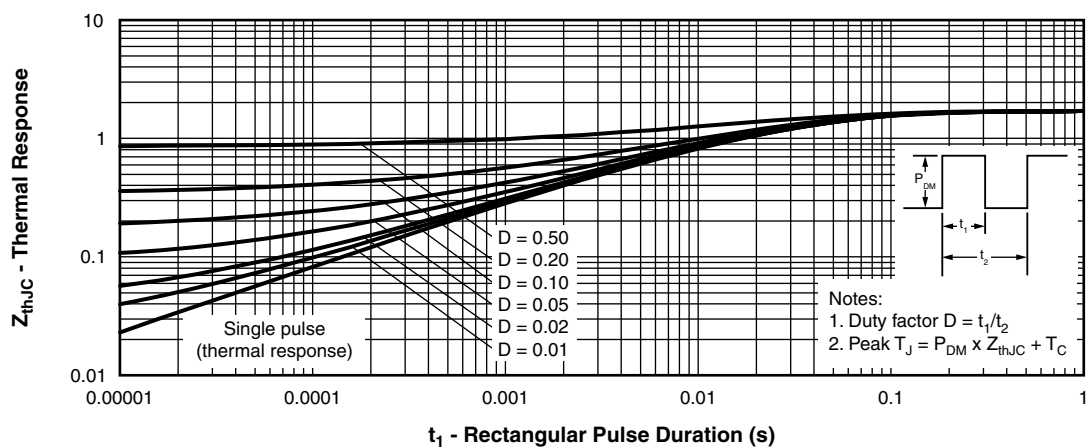


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics (Per Leg)

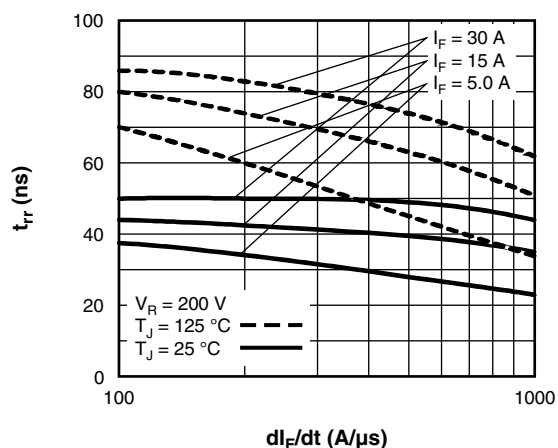
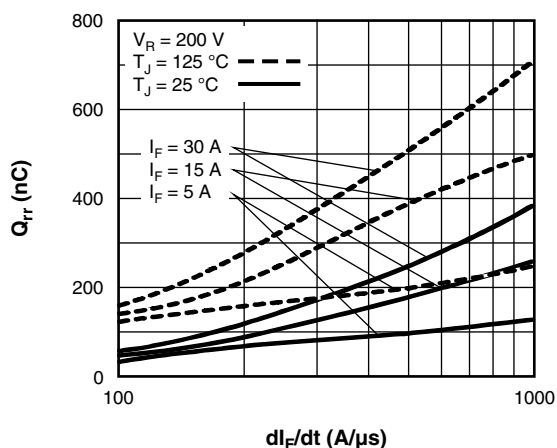
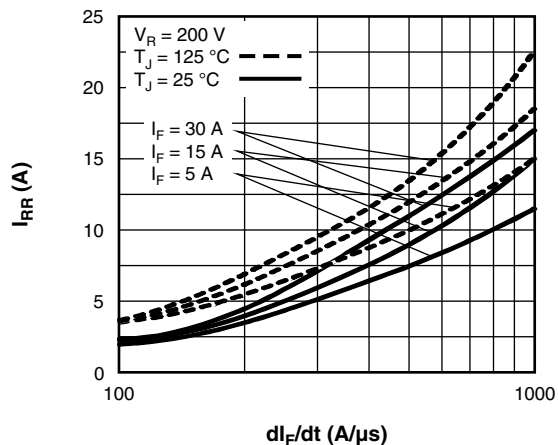
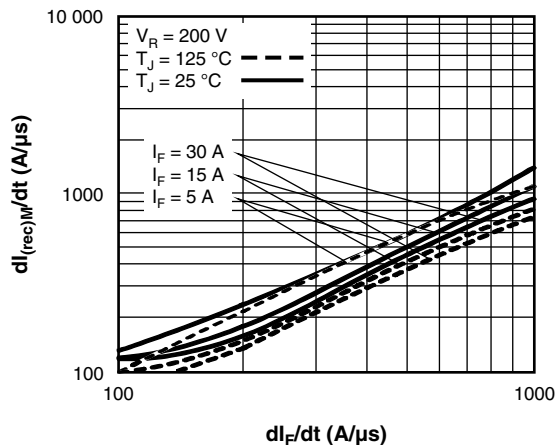
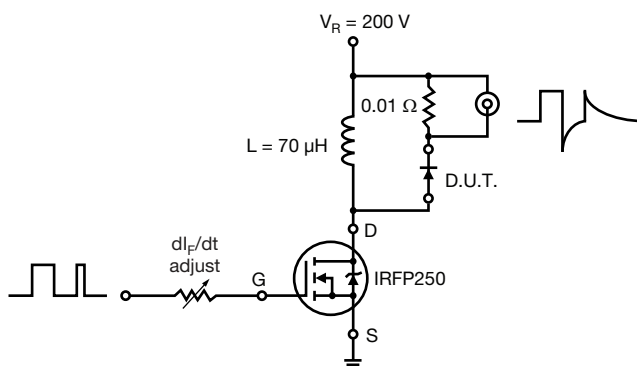

Fig. 5 - Typical Reverse Recovery Time vs.  $dI_F/dt$  (Per Leg)

Fig. 7 - Typical Stored Charge vs.  $dI_F/dt$  (Per Leg)

Fig. 6 - Typical Recovery Current vs.  $dI_F/dt$  (Per Leg)

Fig. 8 - Typical  $dI_{recM}/dt$  vs.  $dI_F/dt$  (Per Leg)


Fig. 9 - Reverse Recovery Parameter Test Circuit

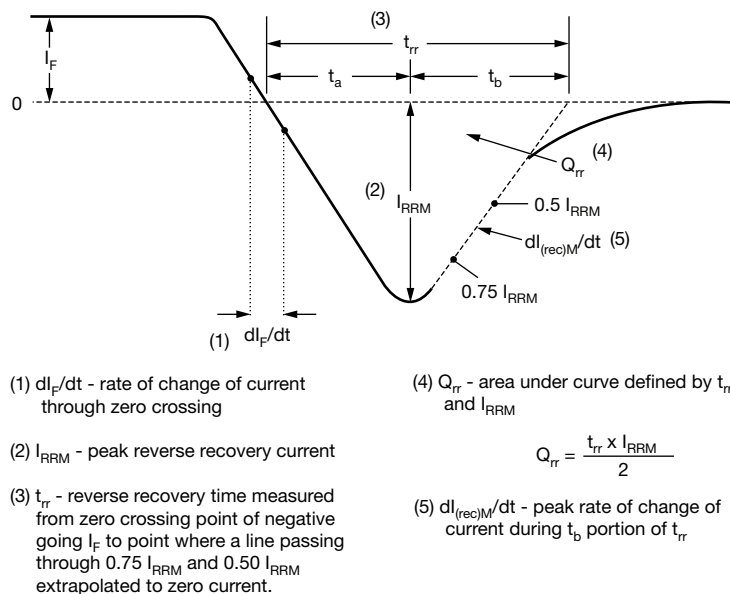


Fig. 10 - Reverse Recovery Waveform and Definitions

## ORDERING INFORMATION TABLE

| Device code | VS- | HF | A | 30 | TA | 60 | C | PbF |
|-------------|-----|----|---|----|----|----|---|-----|
|             | 1   | 2  | 3 | 4  | 5  | 6  | 7 | 8   |

- 1** - Vishay Semiconductors product
- 2** - HEXFRED® family
- 3** - Electron irradiated
- 4** - Current rating (30 = 30 A)
- 5** - Package:  
TA = TO-220AB
- 6** - Voltage rating (60 = 600 V)
- 7** - Circuit configuration:  
C = common cathode
- 8** - Environmental digit:  
PbF = lead (Pb)-free and RoHS-compliant  
-N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

| ORDERING INFORMATION (Example) |                  |                        |                         |
|--------------------------------|------------------|------------------------|-------------------------|
| PREFERRED P/N                  | QUANTITY PER T/R | MINIMUM ORDER QUANTITY | PACKAGING DESCRIPTION   |
| VS-HFA30TA60CPbF               | 50               | 1000                   | Antistatic plastic tube |
| VS-HFA30TA60C-N3               | 50               | 1000                   | Antistatic plastic tube |

| LINKS TO RELATED DOCUMENTS |             |                                                                        |
|----------------------------|-------------|------------------------------------------------------------------------|
| Dimensions                 |             | <a href="http://www.vishay.com/doc?95222">www.vishay.com/doc?95222</a> |
| Part marking information   | TO-220ABPbF | <a href="http://www.vishay.com/doc?95225">www.vishay.com/doc?95225</a> |
|                            | TO-220AB-N3 | <a href="http://www.vishay.com/doc?95028">www.vishay.com/doc?95028</a> |

## TO-220AB

**DIMENSIONS** in millimeters and inches



| SYMBOL | MILLIMETERS |       | INCHES |       | NOTES |
|--------|-------------|-------|--------|-------|-------|
|        | MIN.        | MAX.  | MIN.   | MAX.  |       |
| A      | 4.25        | 4.65  | 0.167  | 0.183 |       |
| A1     | 1.14        | 1.40  | 0.045  | 0.055 |       |
| A2     | 2.56        | 2.92  | 0.101  | 0.115 |       |
| b      | 0.69        | 1.01  | 0.027  | 0.040 |       |
| b1     | 0.38        | 0.97  | 0.015  | 0.038 | 4     |
| b2     | 1.20        | 1.73  | 0.047  | 0.068 |       |
| b3     | 1.14        | 1.73  | 0.045  | 0.068 | 4     |
| c      | 0.36        | 0.61  | 0.014  | 0.024 |       |
| c1     | 0.36        | 0.56  | 0.014  | 0.022 | 4     |
| D      | 14.85       | 15.25 | 0.585  | 0.600 | 3     |
| D1     | 8.38        | 9.02  | 0.330  | 0.355 |       |
| D2     | 11.68       | 12.88 | 0.460  | 0.507 | 6     |

| SYMBOL | MILLIMETERS |       | INCHES     |       | NOTES |
|--------|-------------|-------|------------|-------|-------|
|        | MIN.        | MAX.  | MIN.       | MAX.  |       |
| E      | 10.11       | 10.51 | 0.398      | 0.414 | 3, 6  |
| E1     | 6.86        | 8.89  | 0.270      | 0.350 | 6     |
| E2     | -           | 0.76  | -          | 0.030 | 7     |
| e      | 2.41        | 2.67  | 0.095      | 0.105 |       |
| e1     | 4.88        | 5.28  | 0.192      | 0.208 |       |
| H1     | 6.09        | 6.48  | 0.240      | 0.255 | 6, 7  |
| L      | 13.52       | 14.02 | 0.532      | 0.552 |       |
| L1     | 3.32        | 3.82  | 0.131      | 0.150 | 2     |
| Ø P    | 3.54        | 3.73  | 0.139      | 0.147 |       |
| Q      | 2.60        | 3.00  | 0.102      | 0.118 |       |
| θ      | 90° to 93°  |       | 90° to 93° |       |       |

### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- (7) Dimensions E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC TO-220, except A2 (maximum) and D2 (minimum) where dimensions are derived from the actual package outline



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